

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|-------|---|---|------------------|---------|------------------|
| L2 | 99 | @ad<="20040301" and ("thermo-electrical" or thermoelectric or "thermo-electric") with (diamond or SiC) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/30 07:43 |
| L3 | 0 | @ad<="20040301" and ("thermo-electrical" or thermoelectric or "thermo-electric") with "coil structure" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/30 07:15 |
| L4 | 394 | @ad<="20040301" and ("thermo-electrical" or thermoelectric or "thermo-electric") with coil | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/30 07:16 |
| L6 | 20 | @ad<="20040301" and "semiconductor" same ("thermo-electrical" or thermoelectric or "thermo-electric") with coil | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/30 07:16 |
| L8 | 20 | @ad<="20040301" and "semiconductor" same ("thermo-electrical" or thermoelectric or "thermo-electric") with (coil or maze) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/30 07:16 |
| L9 | 19729 | @ad<="20040301" and wafer with semiconductor with "integrated circuit" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/30 07:46 |
| L10 | 1 | @ad<="20040301" and thermoelectric same wafer with semiconductor with "integrated circuit" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/30 07:44 |
| L11 | 6 | @ad<="20040301" and cooler same wafer with semiconductor with "integrated circuit" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/30 07:46 |
| S1 | 2043 | @ad<="20040301" and (257/717-718).ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 09:03 |
| S2 | 1319 | @ad<="20040301" and (257/706).ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 05:09 |

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| S3 | 714 | @ad<="20040301" and (257/720). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 05:10 |
| S4 | 812 | @ad<="20040301" and (257/675). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:11 |
| S5 | 147 | @ad<="20040301" and (257/625). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:48 |
| S6 | 163 | @ad<="20040301" and (257/276). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 05:33 |
| S7 | 625 | @ad<="20040301" and (438/122). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 05:10 |
| S8 | 1452 | @ad<="20040301" and (174/16.3). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 05:10 |
| S9 | 176 | @ad<="20040301" and (228/222). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 05:11 |
| S10 | 18 | @ad<="20040301" and (361/274. 3).ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 05:11 |
| S11 | 767 | @ad<="20040301" and (361/697). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:07 |
| S12 | 341 | @ad<="20040301" and (361/702). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 05:11 |
| S13 | 671 | @ad<="20040301" and (361/709). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 05:12 |

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| S14 | 11 | @ad<="20040301" and (361/514). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 05:12 |
| S15 | 439 | @ad<="20040301" and 'thermal' with 'electrical' and 'semiconductor body' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/28 15:11 |
| S16 | 16 | @ad<="20040301" and 'thermal' with 'electrical' and 'semiconductor body' and 'trough' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 05:36 |
| S17 | 0 | @ad<="20040301" and 'heat sink' same ('SiC' or 'diamond') and 'semiconductor body' and 'trough' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 05:37 |
| S18 | 28 | @ad<="20040301" and 'heat sink' same ('SiC' or 'diamond') and 'semiconductor body' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 05:45 |
| S19 | 169 | @ad<="20040301" and 'thermo-electrical' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:12 |
| S20 | 22 | @ad<="20040301" and 'thermo-electrical' and 'heat sink' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:13 |
| S21 | 0 | @ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive' and 'heat transfer' same 'helix' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:08 |
| S22 | 0 | @ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive' and 'heat transfer' same 'maze' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:07 |
| S23 | 0 | @ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive' and 'heat transfer' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:07 |
| S24 | 0 | @ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:07 |

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| S26 | 5 | @ad<="20040301" and 'semiconductor' and 'heat sink' and 'conductive' and 'heat transfer' same 'helix' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:09 |
| S27 | 7 | @ad<="20040301" and 'semiconductor' and 'heat sink' and 'conductive' and 'heat transfer' same 'maze' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:11 |
| S28 | 4 | @ad<="20040301" and 'heat regulating' and 'semiconductor' and 'heat sink' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:17 |
| S29 | 0 | @ad<="20040301" and 'heat regulating device' and 'IC' and 'heat sink' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:17 |
| S30 | 0 | @ad<="20040301" and 'heat regulating' and 'IC' and 'heat sink' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:18 |
| S31 | 7 | @ad<="20040301" and 'heat regulating' and 'chip' and 'heat sink' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:19 |
| S32 | 0 | @ad<="20040301" and 'heat regulating device' same 'maze' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:20 |
| S33 | 0 | @ad<="20040301" and 'heat regulating device' same 'helix' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:44 |
| S34 | 55 | @ad<="20040301" and 'heat sink' same 'helix' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:25 |
| S35 | 8 | @ad<="20040301" and 'heat sink' same 'maze' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:32 |
| S36 | 9 | @ad<="20040301" and 'heat sink' same 'helix' and 'semiconductor' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:25 |

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| S37 | 0 | @ad<="20040301" and 'thermal' with 'regulating' same 'semiconducotr' same ('heat sink' or 'heat spreader') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:46 |
| S38 | 0 | @ad<="20040301" and 'thermal' with 'control' same 'semiconducotr' same ('heat sink' or 'heat spreader') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:46 |
| S39 | 0 | @ad<="20040301" and 'heat' with 'control' same 'semiconducotr' same ('heat sink' or 'heat spreader') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:46 |
| S40 | 4 | @ad<="20040301" and 'thermal' with 'regulating' same 'semiconductor' same ('heat sink' or 'heat spreader') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:46 |
| S41 | 737 | @ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'semiconductor' same ('heat sink' or 'heat spreader') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:47 |
| S42 | 220 | @ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'semiconductor device' same ('heat sink' or 'heat spreader') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:47 |
| S43 | 145 | @ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'IC' same ('heat sink' or 'heat spreader') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:48 |
| S44 | 424 | @ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'chip' same ('heat sink' or 'heat spreader') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 06:48 |
| S45 | 1508 | @ad<="20040301" and (361/695). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:21 |
| S46 | 144 | @ad<="20040301" and (361/696). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:07 |
| S47 | 1 | "6016250".PN. | USPAT; USOCR | OR | ON | 2005/10/02 07:07 |
| S48 | 1 | "5773755".PN. | USPAT; USOCR | OR | ON | 2005/10/02 07:07 |

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| S49 | 1 | "5463529".PN. | USPAT; USOCR | OR | ON | 2005/10/02 07:08 |
| S51 | 181 | @ad<="20040301" and ('array' or 'matrix') with 'heat sink' same 'semiconductor device' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:16 |
| S52 | 24 | @ad<="20040301" and 'matrix' with 'heat sink' same 'semiconductor device' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:20 |
| S53 | 522 | @ad<="20040301" and 'matrix' with 'heat sink' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:20 |
| S54 | 394 | @ad<="20040301" and (361/694). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:21 |
| S55 | 1 | "5988488".PN. | USPAT; USOCR | OR | ON | 2005/10/02 07:26 |
| S56 | 1 | "5848467".PN. | USPAT; USOCR | OR | ON | 2005/10/02 07:26 |
| S57 | 1162 | @ad<="20040301" and (257/718). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:28 |
| S58 | 952 | @ad<="20040301" and (257/717). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:28 |
| S59 | 711 | @ad<="20040301" and (257/718). ccls. and 'heat sink' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:28 |
| S60 | 283 | @ad<="20040301" and (257/718). ccls. and 'heat sink' same 'semiconductor' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:29 |
| S61 | 5 | @ad<="20040301" and 'maze' with 'heat sink' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:42 |

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| S62 | 20 | @ad<="20040301" and 'helix' with 'heat sink' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/02 07:32 |
| S63 | 35 | @ad<="20040301" and 'thermal control' with 'IC' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 09:32 |
| S64 | 1 | "6016250".PN. | USPAT; USOCR | OR | ON | 2005/10/02 07:47 |
| S65 | 943 | @ad<="20040301" and (257/719). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 09:08 |
| S67 | 1 | @ad<="20040301" and (257/719). ccls. and 'heat' same dissipat\$4 same 'silicon carbide' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 09:06 |
| S68 | 32 | @ad<="20040301" and (257/719). ccls. and 'diamond' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 09:16 |
| S71 | 1 | @ad<="20040301" and 'therm' with 'sensor' and ('diamond' or 'silicon carbide') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 09:19 |
| S75 | 45 | @ad<="20040301" and 'semiconductor' and ('thermal' or 'thermo') with 'electrical' same 'heat flow' and ('diamond' or 'silicon carbide') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 09:22 |
| S76 | 1 | "5712448".PN. | USPAT; USOCR | OR | ON | 2005/12/27 09:26 |
| S77 | 1 | "5705770".PN. | USPAT; USOCR | OR | ON | 2005/12/27 09:26 |
| S78 | 143 | @ad<="20040301" and 'thermal control' with 'semiconductor' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 09:33 |
| S79 | 35 | @ad<="20040301" and 'thermal control' with 'ic' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 09:35 |

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| S80 | 2 | @ad<="20040301" and 'Controlling hot spots' and ('diamond' or 'silicon carbide') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 09:36 |
| S81 | 124 | @ad<="20040301" and 'semiconductor' same 'hot spots' and ('diamond' or 'silicon carbide') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 09:49 |
| S82 | 1 | "6521991".PN. | USPAT; USOCR | OR | ON | 2005/12/27 09:39 |
| S83 | 1 | "6334311".PN. | USPAT; USOCR | OR | ON | 2005/12/27 09:40 |
| S84 | 1 | "6322626".PN. | USPAT; USOCR | OR | ON | 2005/12/27 09:41 |
| S85 | 1 | "6199927".PN. | USPAT; USOCR | OR | ON | 2005/12/27 09:41 |
| S86 | 13 | @ad<="20040301" and 'semiconductor' same 'hot spots' same ('diamond' or 'silicon carbide') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:08 |
| S87 | 2 | @ad<="20040301" and 'semiconductor' same 'thermo-electric' same ('diamond' or 'silicon carbide') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:09 |
| S88 | 141 | @ad<="20040301" and 'semiconductor' and 'thermo-electric' and ('diamond' or 'silicon carbide') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:10 |
| S89 | 7 | @ad<="20040301" and 'semiconductor' and 'thermo-electric' same ('diamond' or 'silicon carbide') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:10 |
| S90 | 12 | @ad<="20040301" and 'semiconductor' same 'thermo-electric' and ('diamond' or 'silicon carbide') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:11 |
| S91 | 171 | @ad<="20040301" and 'thermo-electrical' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:12 |
| S92 | 23 | @ad<="20040301" and 'thermo-electrical' and 'heat sink' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:14 |

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| S93 | 776 | @ad<="20040301" and 'thermo' with electric\$2 and 'heat sink' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:13 |
| S94 | 501 | @ad<="20040301" and 'thermo-electric' and 'heat sink' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:34 |
| S95 | 1 | @ad<="20040301" and 'thermo-electric' and 'heat sink' same 'silicon carbide' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:14 |
| S96 | 27 | @ad<="20040301" and 'thermo-electric' and 'heat sink' and 'silicon carbide' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:26 |
| S97 | 74 | @ad<="20040301" and 'thermo-electric' and 'heat sink' and ('silicon carbide' or 'diamond') | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:26 |
| S98 | 9 | @ad<="20040301" and 'thermo-electric' and 'heat sink' same 'diamond' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:30 |
| S99 | 1 | @ad<="20040301" and 'thermo-electric' and 'heat sink' same 'carbide' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:35 |
| S10 0 | 27 | @ad<="20040301" and 'thermo-electric' and 'heat sink' and 'silicon carbide' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:45 |
| S10 1 | 4 | ((("6098408") or ("5940784")).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/27 10:45 |
| S10 2 | 1 | "5940784".PN. | USPAT; USOCR | OR | ON | 2005/12/27 10:47 |
| S10 3 | 1 | "5867990".PN. | USPAT; USOCR | OR | ON | 2005/12/27 10:47 |

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| S10 4 | 410 | @ad<="20040301" and (62/3.7). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/27 10:48 |
| S10 5 | 1 | "5822993".PN. | USPAT; USOCR | OR | ON | 2005/12/27 10:48 |
| S10 6 | 1 | "5867990".PN. | USPAT; USOCR | OR | ON | 2005/12/27 10:48 |
| S10 7 | 1 | "5690849".PN. | USPAT; USOCR | OR | ON | 2005/12/27 10:49 |
| S10 8 | 432 | @ad<="20040301" and ("SiC" or diamond) with therm\$2 with electrical and semiconductor | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/28 15:25 |
| S10 9 | 0 | @ad<="20040301" and ("SiC" or diamond) with "thermo-electrical" and semiconductor | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/28 15:13 |
| S11 0 | 0 | @ad<="20040301" and ("SiC" or diamond) with "thermo-electrical" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/28 15:13 |
| S11 1 | 171 | @ad<="20040301" and "thermo-electrical" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/28 15:47 |
| S11 2 | 33 | @ad<="20040301" and "thermo-electrical" and semiconductor | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/28 15:15 |
| S11 4 | 37 | @ad<="20040301" and "thermo-electrical" and (semiconductor or "IC") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/28 15:18 |
| S11 5 | 1 | ANTONOVSKA | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/28 15:21 |
| S11 7 | 285 | @ad<="20040301" and ("SiC" or diamond) with therm\$2 with electric\$2 and semiconductor and cool\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/28 15:25 |

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|----------|------|---|---|----|-----|------------------|
| S11 8 | 100 | @ad<="20040301" and ("SiC" or diamond) with therm\$2 with electric\$2 and (semiconductor or "IC") same cool\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/28 15:28 |
| S11 9 | 26 | @ad<="20040301" and ("SiC" or diamond) with ("therm\$2 with electric\$2" or thermoelectric or "thermo-electrical") and (semiconductor or "IC") same cool\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/28 15:46 |
| S12 0 | 2237 | @ad<="20040301" and (62/259.2)". ccls" or (62/3.7).ccls. or (62/3.2). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/28 15:46 |
| S12 1 | 67 | @ad<="20040301" and ("thermo-electrical" or thermoelectric) same cool\$3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/28 15:48 |
| S12 4 | 109 | @ad<="20040301" and ("thermo-electrical" or thermoelectric) same cool\$3 same "IC" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/30 07:13 |
| S12 5 | 8 | ((("6,196,002") or ("5,569,950") or ("5,032,897") or ("6,094,919")).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/04/28 16:10 |
| S12 6 | 1 | "6222113".PN. | USPAT; USOCR | OR | ON | 2006/04/28 16:12 |
| S12 7 | 1 | "6121539".PN. | USPAT; USOCR | OR | ON | 2006/04/28 16:12 |
| S12 8 | 1 | "5956569".PN. | USPAT; USOCR | OR | ON | 2006/04/28 16:13 |